



NSAI
Standards

Irish Standard
I.S. EN 61191-2:2013

Printed board assemblies -- Part 2:
Sectional specification - Requirements
for surface mount soldered assemblies
(IEC 61191-2:2013 (EQV))

I.S. EN 61191-2:2013

Incorporating amendments/corrigenda issued since publication:

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English version

**Printed board assemblies -
Part 2: Sectional specification -
Requirements for surface mount soldered assemblies
(IEC 61191-2:2013)**

Ensembles de cartes imprimées -
Partie 2: Spécification intermédiaire -
Exigences relatives à l'assemblage par
brasage pour montage en surface
(CEI 61191-2:2013)

Elektronikaufbauten auf Leiterplatten -
Teil 2: Rahmenspezifikation -
Anforderungen an gelötete Baugruppen in
Oberflächenmontage
(IEC 61191-2:2013)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 91/1091/FDIS, future edition 2 of IEC 61191-2, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61191-2:2013.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2014-04-10
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2016-07-10

This document supersedes EN 61191-2:1998.

EN 61191-2:2013 includes the following significant technical changes with respect to EN 61191-2:1998:

- IPC-A-610 on workmanship has been included as a normative reference;
- some of the terminology used in the document has been updated;
- references to EN standards have been corrected;
- the use of lead-free solder paste and plating are addressed.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC [and/or CEN] shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 61191-2:2013 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61191-1	2013	Printed board assemblies Part 1: Generic specification - Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies	EN 61191-1	2013
IPC-A-610E	2010	Acceptability of Electronic Assemblies	-	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARD ASSEMBLIES –

**Part 2: Sectional specification –
Requirements for surface mount soldered assemblies**

FOREWORD

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International Standard IEC 61191-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This second edition cancels and replaces the first edition, published in 1998, and constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- IPC-A-610 on workmanship has been included as a normative reference;
- some of the terminology used in the document has been updated;
- references to IEC standards have been corrected;
- the use of lead-free solder paste and plating are addressed.

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The text of this standard is based on the following documents:

FDIS	Report on voting
91/1091/FDIS	91/1103/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61191 under the general title *Printed board assemblies* can be found in the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
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